

**Amendments to the Specification:**

Please amend the specification as follows:

On page 6, please replace the paragraph that starts on line 6 with the phrase – "According to another embodiment" – and ends on line 18 with the words – "single adhesive" – with the following amended paragraph:

"According to another embodiment of the present invention, there is provided an adhesive article comprising a heat curable adhesive layer including a heat curable adhesive composition which comprises a caprolactone-modified epoxy resin and a tack reducing component, and a backing layer carrying said adhesive layer on at least a portion of the backing layer. In such adhesive articles comprising a tack reducing component, the tackiness of the adhesive may be lowered. As a result, if this adhesive article is used as a tape for dicing and die-bonding in manufacturing a semiconductor apparatus, the following advantages are obtained. After heat bonding of a wafer to the adhesive layer and dicing the wafer into chips, the adhesive layer along with each of the chips is easily released from the backing layer, and the chip can be die-bonded to a substrate for a semiconductor apparatus via the adhesive layer without interruption. With the present invention, the manufacturing process from the step of dicing into chips to the step of die-bonding can be carried out with a single adhesive."

On page 21, please replace the paragraph that starts on line 29 with the phrase – "(Embodiment 2)" – and ends on line 30 with the words – "reducing component" – with the following amended paragraph:

"(Embodiment 2) A heat curable adhesive composition according to Embodiment 1, wherein said tack reducing component is a tack reducing compound."

On page 22, please replace the paragraph that starts on line 31 with the phrase – "(Embodiment 13)" – and ends on line 32 with the words – "acid adduct" – with the following amended paragraph:

"(Embodiment 13) An adhesive article according to Embodiment 12, wherein said tack reducing compound is a melamine/isocyanuric acid adduct."

On page 27, please replace the paragraph that starts on line 14 with the word – "laminating" – and ends on line 18 with the word – "stretched" – with the following amended paragraph:

"laminating, on one surface of a semiconductor wafer which has a plurality of said semiconductor components formed thereon, an adhesive article comprising a heat curable adhesive layer comprising a caprolactone-modified epoxy resin, and a stretchable backing layer carrying said adhesive layer having an elongation of no less than 10% upon stretching."